

LEADED

BGA SOLDER PASTE

● ● ●
Sn63/Pb37

Melting point 183°C



Product Usage

● ● ●
TIN PASTE

Type number	BST-506
Types of	Solder Paste
Composition	Sn63/Pb37
Melting point	183°C
G.W.	50g
size	36*36mm



Sn63/Pb37

Melting point at medium temperature

183°C



Low residue



Solder spot bright

Rapid welding

Welding requirements for a wide range of products



**SMT
patch**



**LED
patch**



**BGA
welding**



Product List

G.W.:50g

